



	<b>XBB170</b>	<b>Units</b>
Load Voltage	350	V
Load Current	100	mA
Max R <sub>ON</sub>	50	Ω

### Description

XBB170 is a 350V, 100mA, 50Ω 2-Form-B relay. It provides an economical solution for applications requiring two independent Form-B relays where cost is critical.

### Features

- Small 8 Pin DIP Package
- Low Drive Power Requirements (TTL/CMOS Compatible)
- No Moving Parts
- High Reliability
- Arc-Free With No Snubbing Circuits
- 3750V<sub>RMS</sub> Input/Output Isolation
- FCC Compatible
- VDE Compatible
- No EMI/RFI Generation
- Machine Insertable, Wave Solderable
- Surface Mount and Tape & Reel Versions Available

### Applications

- Telecommunications
  - Telecom Switching
  - Tip/Ring Circuits
  - Modem Switching (Laptop, Notebook, Pocket Size)
  - Hookswitch
  - Dial Pulsing
  - Ground Start
  - Ringer Injection
- Instrumentation
  - Multiplexers
  - Data Acquisition
  - Electronic Switching
  - I/O Subsystems
  - Meters (Watt-Hour, Water, Gas)
- Medical Equipment—Patient/Equipment Isolation
- Security
- Aerospace
- Industrial Controls

### Approvals

- UL Recognized: File Number E76270
- CSA Certified: File Number LR 43639-10
- BSI Certified to:
  - BS EN 60950:1992 (BS7002:1992)  
Certificate #: 7344
  - BS EN 41003:1993  
Certificate #: 7344

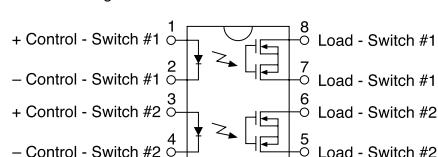
### Ordering Information

<b>Part #</b>	<b>Description</b>
XBB170	8 Pin DIP (50/Tube)
XBB170P	8 Pin Flatpack (50/Tube)
XBB170PTR	8 Pin Flatpack (1000/Reel)
XBB170S	8 Pin Surface Mount (50/Tube)
XBB170STR	8 Pin Surface Mount (1000/Reel)

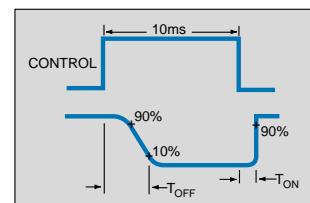
### Pin Configuration

#### XBB170 Pinout

AC/DC Configuration



#### Switching Characteristics of Normally Closed (Form B) Devices



**Absolute Maximum Ratings (@ 25° C)**

Parameter	Min	Typ	Max	Units
Input Power Dissipation	-	-	150 <sup>1</sup>	mW
Input Control Current Peak (10ms)	-	-	50	mA
Reverse Input Voltage	-	-	5	V
Total Power Dissipation	-	-	800 <sup>2</sup>	mW
Isolation Voltage Input to Output	3750	-	-	$V_{RMS}$
Operational Temperature	-40	-	+85	°C
Storage Temperature	-40	-	+125	°C
Soldering Temperature				
DIP Package	-	-	+260	°C
Surface Mount Package (10 Seconds Max.)	-	-	+220	°C

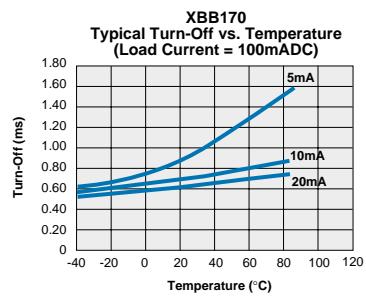
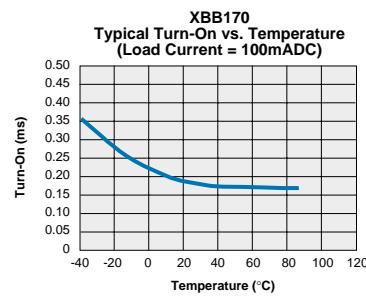
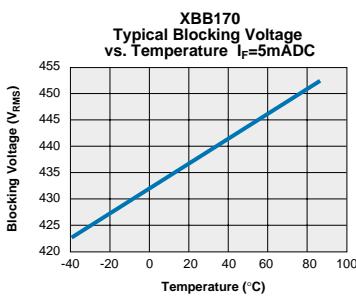
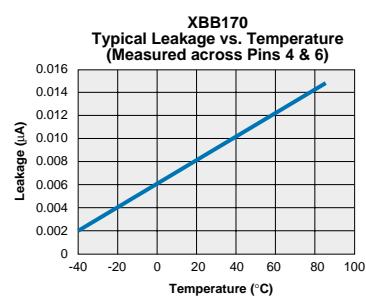
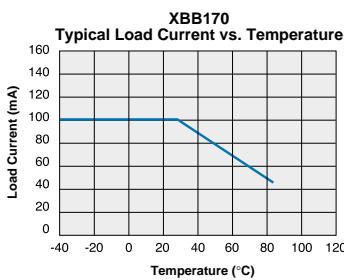
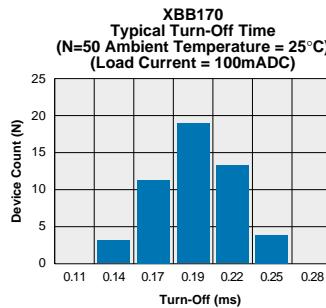
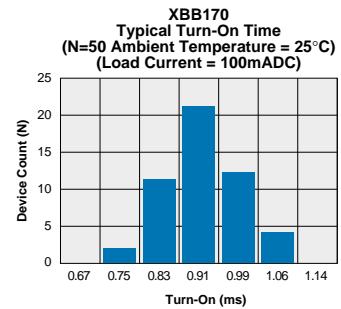
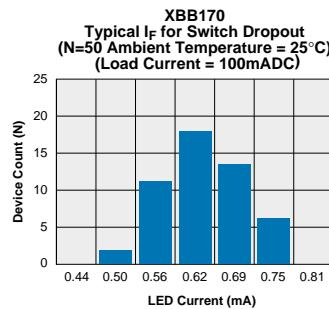
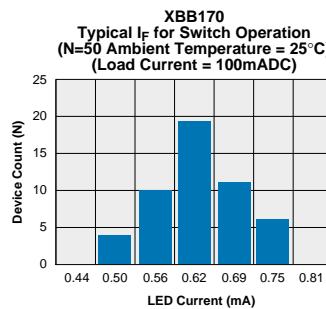
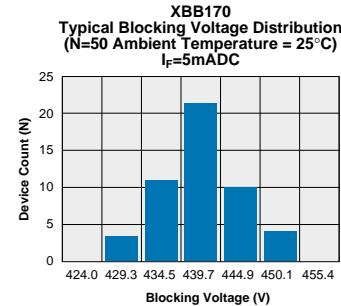
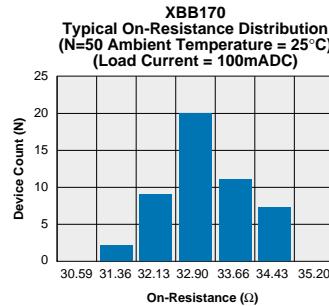
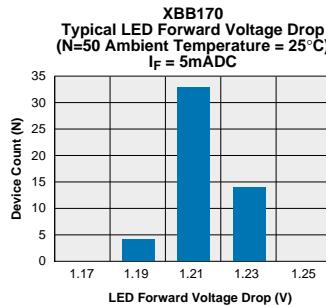
<sup>1</sup> Derate Linearly 1.33 mw/°C<sup>2</sup> Derate Linearly 6.67 mw/°C

*Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this data sheet is not implied. Exposure of the device to the absolute maximum ratings for an extended period may degrade the device and effect its reliability.*

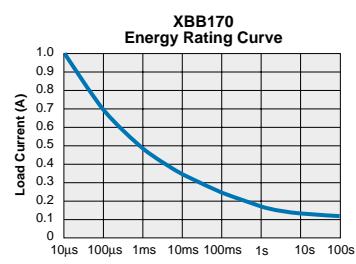
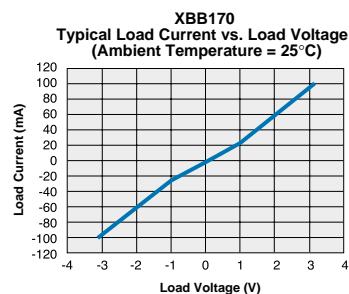
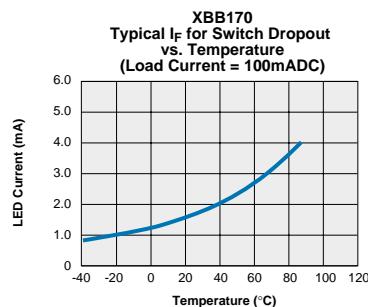
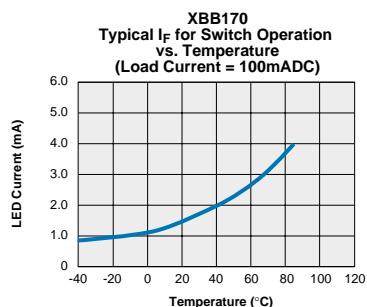
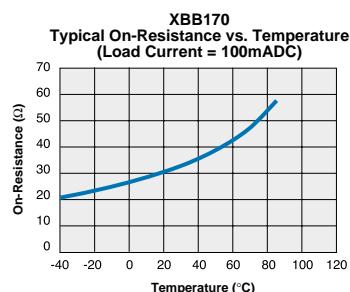
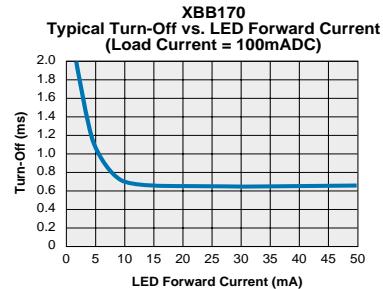
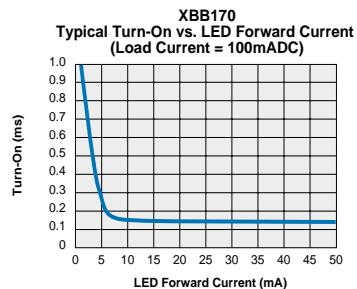
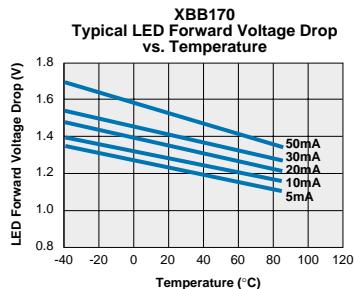
**Electrical Characteristics**

Parameter	Conditions	Symbol	Min	Typ	Max	Units
<b>Output Characteristics @ 25°C</b>						
Load Voltage (Peak)	-	$V_L$	-	-	350	V
Load Current* (Continuous)	-	$I_L$	-	-	100	mA
AC/DC Configuration						
Peak Load Current	10ms	$I_{LPK}$	-	-	350	mA
On-Resistance						
AC/DC Configuration	$I_L=120\text{mA}$	$R_{ON}$	-	33	50	Ω
Off-State Leakage Current	$V_L=350\text{V}$	-	-	-	1	μA
Switching Speeds						
Turn-On	$I_F = 5\text{mA}, V_L=10\text{V}$	$T_{ON}$	-	-	5	ms
Turn-Off	$I_F = 5\text{mA}, V_L=10\text{V}$	$T_{OFF}$	-	-	5	ms
Output Capacitance	50V; f = 1MHz	$C_{OUT}$	-	25	-	pF
<b>Input Characteristics @ 25°C</b>						
Input Control Current	$I_L = 120\text{mA}$	$I_F$	5	-	50	mA
Input Dropout Current	-	$I_F$	0.4	0.7	-	mA
Input Voltage Drop	$I_F = 5\text{mA}$	$V_F$	0.9	1.2	1.4	V
Reverse Input Voltage	-	$V_R$	-	-	5	V
Reverse Input Current	$V_R = 5\text{V}$	$I_R$	-	-	10	μA
<b>Common Characteristics @ 25°C</b>						
Input to Output Capacitance	-	$V_{C/O}$	-	3	-	pF
Input to Output Isolation	-	$V_{I/O}$	3750	-	-	$V_{RMS}$

\*Note: If both poles operate simultaneously load current must be derated so as not to exceed the package power dissipation value.

**PERFORMANCE DATA\***


\*The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

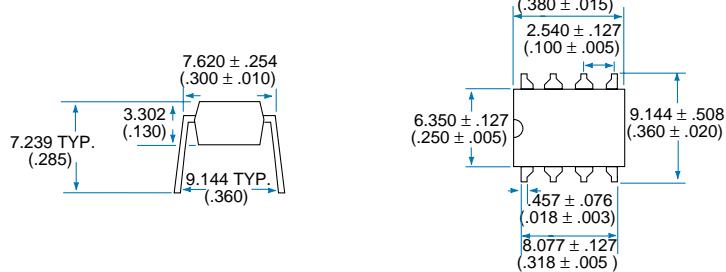
**PERFORMANCE DATA\***


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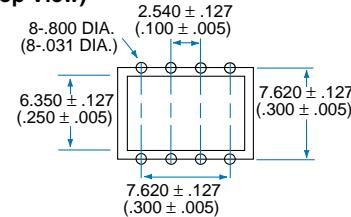


### Mechanical Dimensions

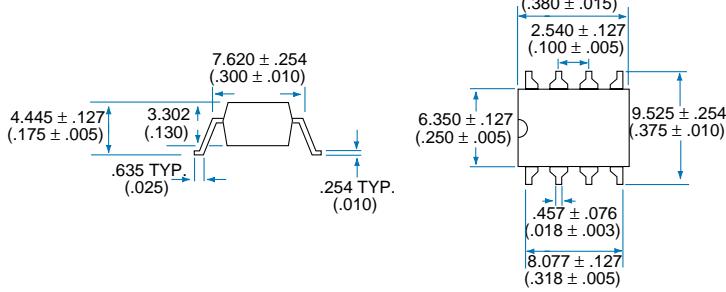
#### 8 Pin DIP Through Hole (Standard)



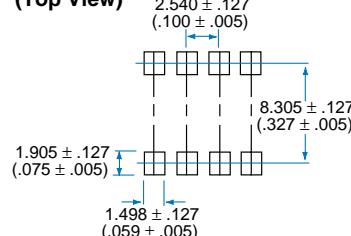
#### PC Board Pattern (Top View)



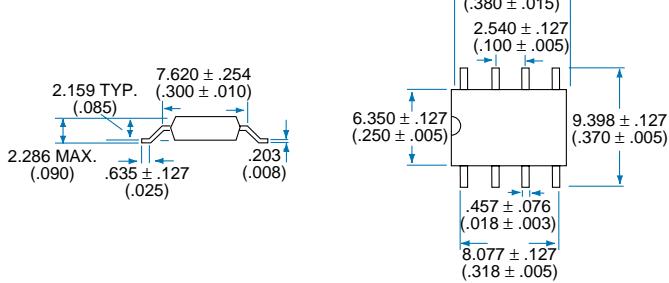
#### 8 Pin DIP Surface Mount ("S" Suffix)



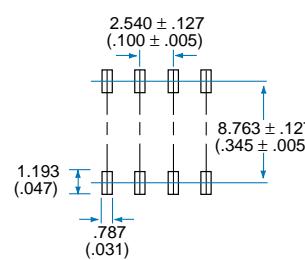
#### PC Board Pattern (Top View)



#### 8 Pin Flatpack ("P" Suffix)



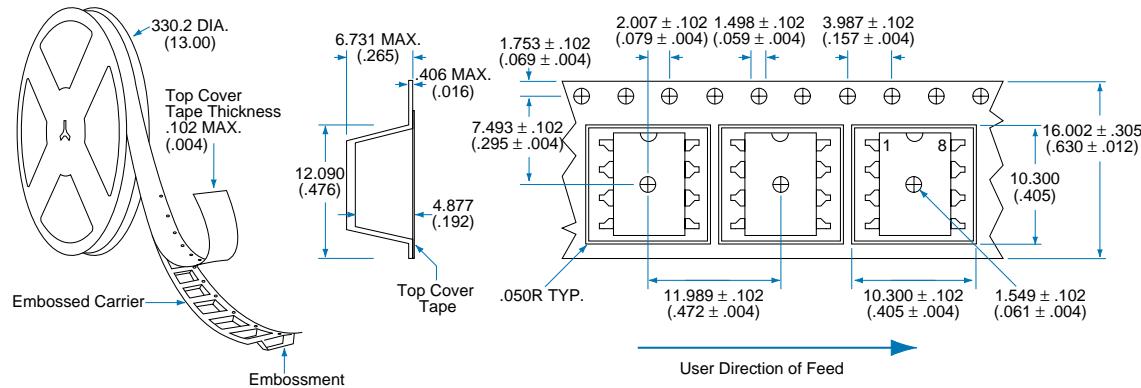
#### PC Board Pattern (Top View)



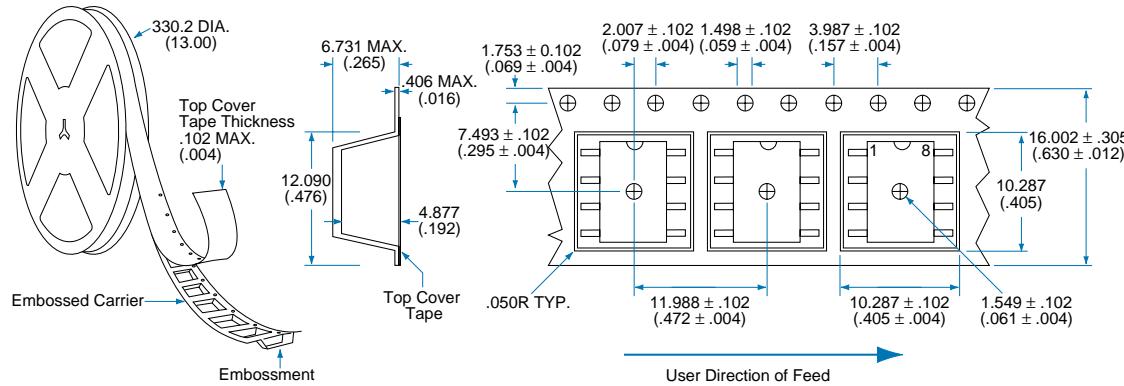
Dimensions  
mm  
(inches)

### Mechanical Dimensions

#### Tape and Reel Packaging for 8 Pin Surface Mount Package



#### Tape and Reel Packaging for 8 Pin Flatpack Package



Dimensions  
mm  
(inches)



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